



Package Description Table

IDT ID	Abbr	Description	IDT ID	Abbr	Description
D	CERDIP	Ceramic Dual In-Line Package	TP	PDIP	Plastic Dual In-line Package
TD	CERDIP	Ceramic Dual In-Line Package	J	PLCC	Plastic Leaded Chip Carrier
BC	CABGA	Chip Array Ball Grid Array	PQF	PQFP	Plastic Quad Flat Package
L	LCC	Leadless Chip Carrier (Ceramic) - mil only	SO	SOIC	Small Outline Integrated Circuit (Plastic)
BB	PBGA	Plastic Ball Grid Array	PF	TQFP	PThin Quad Flat Package (Plastic)
BG	PBGA	Plastic Ball Grid Array	TF	TQFP	Thin Quad Flat Package (Plastic)
P	PDIP	Plastic Dual In-line Package	PA	TSSOP	Thin Shrink (Plastic) Small Outline Package

Part Number Description

N = Numeric character

